



MP1501 MTBF Report

by



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1.1	3/7/2025	Update FIT Value for FIL1201	MB

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1 Introduction

1.1 Overview

Failure rates were determined for the components in the Bill of Materials provided by HID Global. The PCA-01049 MP1501. A Mean Time Between Failure (MTBF) calculation was then performed using Telcordia SR332, Issue 4, ARPP Version 12.1a, 2017.

1.2 Scope

This report, prepared by Percept Technology Labs LLC, documents the failure rate analysis and the results of the calculation.

1.3 Definitions

BOM = Bill of Materials

FR = Failure Rate - units are failures/million hours

FIT = Failures in Time - units are failures/billion hours

MTBF = Mean Time Between Failure – units are hours

The predicted elapsed time between inherent failures of a system during operation is called the mean time between failures (MTBF). This is calculated as the arithmetic mean (average) time between failures of a system. The MTBF is typically part of a model that assumes the failed system is immediately repaired (zero elapsed time), as a part of a renewal process. In contrast, the mean time to failure (MTTF), measures average time between failures with the modeling assumption that the failed system is not repaired.

The definition of MTBF depends on the definition of what is considered a system failure. For complex, repairable systems, failures are considered to be those out of design conditions which place the system out of service and into a state for repair. Failures which occur that can be left or maintained in an unrepaired condition, and do not place the system out of service, are not considered failures under this definition. In addition, units that are taken down for routine scheduled maintenance or inventory control are not considered within the definition of failure.

For the purposes of this report, we are using the first definition of failure: that which places the system out of service and in need of repair.

1.4 Company Restricted Information

This document contains confidential and restricted information. Reproduction of this document outside of HID Global or Percept Technology Labs LLC is prohibited.

1.5 Reference Documents

Reference documents for this evaluation included the HID Global PCA-01049 MP1501 Bill of Materials and component specifications.

1.6 Client Information

HID GLOBAL
Unit 3, Cae Gwyrdd
Green Meadow Springs Business Park
CF15 7AB Cardiff
United Kingdom

1.7 Test Entrance Criteria

- All necessary product-related materials and support documentation required for Percept Technology Labs LLC to execute this project.
- Access to a technical resource (person) for operational questions.

1.8 Test Exit Criteria

- All data collected for specified test cases.
- Completed Test Report (This document).

2 Analysis

2.1 General Reliability Prediction Assumptions

- An electronic component can only fail when current is applied.
- The probability of failure for any electronic component is constant throughout its "useful life". The probability of failure is the same from the first it is turned on until the end of its useful life is reached (usually millions of hours of run time).
- $MTBF = 1/\text{failure rate}$. If the failure rate number is obtained from the Telcordia database or the supplier's datasheets it has assumed 100% duty cycle. The failure rate to be used in the MTBF prediction calculation is equal to the base failure rate times the duty cycle.
- Mechanical and electrical wearout are not part of the reliability prediction calculations.

2.2 Environmental Stress Factors

- Ambient temperature = 25°C.
- Electrical Stress is assumed to be 50% for all components.
- Component Quality Level 1 is used for the prediction.
- The Environment is assumed to be Ground, Fixed, Uncontrolled for all components
- The assumed Duty Cycle is 100% for all components.

3 Results:

Table 1: MP1501 Reliability Prediction

P/N	Quantity	Description	FIT
	1	MP1501	2029.673
Failures per Billion Hours			2029.673
MTBF			492,690

Assumptions:

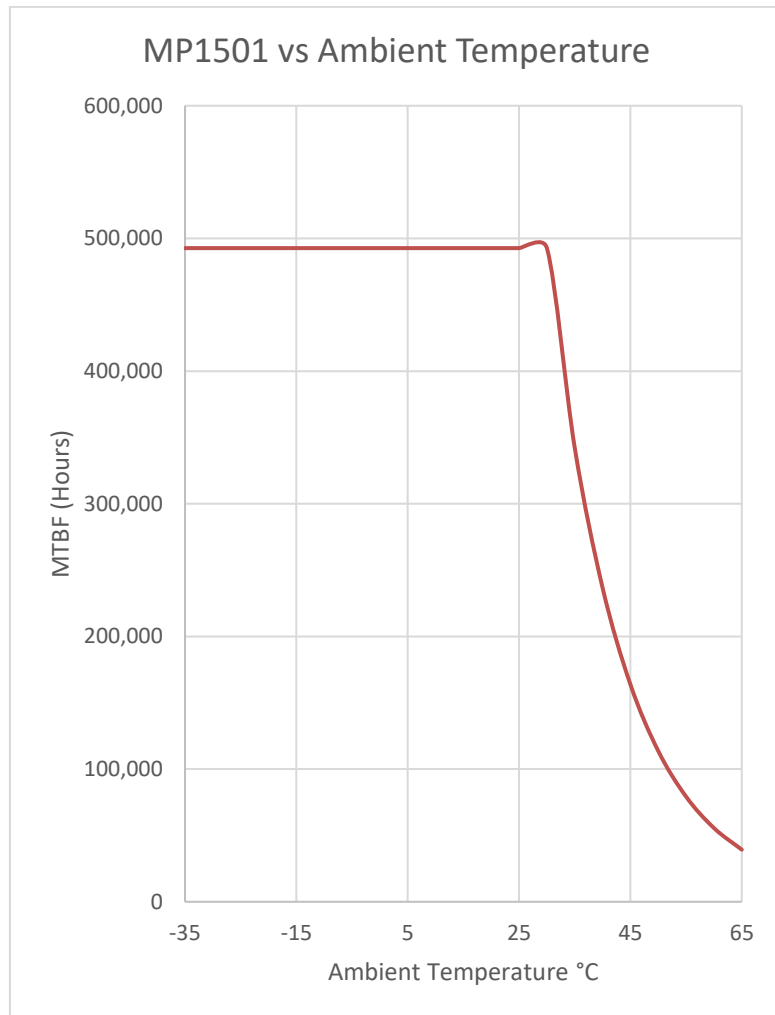
Part Stress Level = 50%

Ambient Temperature = 25°C

Environment = "Ground Fixed, Uncontrolled"

Table 2: MP1501 Prediction vs. Temperature

MP1501 MTBF vs. Temperature		
Ambient	FIT	MTBF
-35	2029.673	492,690
-30	2029.673	492,690
-25	2029.673	492,690
-20	2029.673	492,690
-15	2029.673	492,690
-10	2029.673	492,690
-5	2029.673	492,690
0	2029.673	492,690
5	2029.673	492,690
10	2029.673	492,690
15	2029.673	492,690
20	2029.673	492,690
25	2029.673	492,690
30	2029.673	492,690
35	2923.070	342,106
40	4225.027	236,685
45	6106.299	163,765
50	8800.011	113,636
55	12620.945	79,233
60	17989.744	55,587
65	25462.765	39,273



4 Appendix A — Component Detail Tables

4.1 MP1501

Table 3: MP1501 System Reliability @ Ambient Temp = 25°C

Description	Qty	Ref Design	Device Fit	System Fit
CONN HEADER STRAIGHT THRU HOLE 2.54MM 2-WAY	2	J801,J1202	0.15	0.29
ICD OPTO COUPLER ACPL-217-50BE	1	U500	9.87	9.87
DIODE, LED CLEAR RED, 0805	9	D801,D802,D803,D804,D805,D806,D807,D1404,D1406	0.32	2.87
SW DIP SMT TAPE SEAL 4 POS LF-ROHS	1	SW800	12.18	12.18
DIO TVS UNIDIRECTIONAL 28V DO-214AA(SMB)	2	D303,D1307	0.13	0.25
DIODE TVS 58V 600W UNI-DIR SMB (DO-214AA)	1	D500	0.09	0.09
FILTER FERRITE BEAD 600OHM @ 100MHZ 1A 1206	4	L501,L502,L506,L507	0.25	1.00
TFMR POE 802.3AT ETHERNET 10/100 30W	1	T1000	0.36	0.36
RES SMT_0603 TC200 5% 120 OHM LF-ROHS	1	R1248	0.20	0.20
HDR VT 3.5MM FW2 5A GRN 4POS ROHS	3	TB300,TB1300,TB1400	0.29	0.88
HDR VT 3.5MM FW2 5A GRN 6POS ROHS	2	TB1301,TB1401	0.44	0.88
PTC SMT 30V 50MA FOOTPRINT:1210	2	PTC1300,PTC1301	1.20	2.40
CONN RJ45 VERTW/LED G/Y LF-ROHS	1	J1000	0.37	0.37
CONN VERT USB MICRO-B MLX 105133	1	J1201	0.59	0.59
IC DRIVER 485 HALF-DUPLEX 3.3V SOIC-8	1	U1202	0.01	0.01
DIO BRG SMT 100V1A DF01S	2	BR500,BR501	1.27	2.53
CAP CMK 1812 X7R 2KV10% 2200PF LF-ROHS	2	C501,C509	0.28	0.56
CAP ALM 330UF 16-25V 20% LSR SMT8X10 LF	1	C505	1.34	1.34
INDUCTOR SMT DO1813 0.33UH LF-ROHS	1	L503	0.25	0.25
INDUCTOR CMC POE+ 750MA ROHS	1	L504	0.27	0.27
MODULE POE+ SILVERTEL AG5300 ROHS	1	U501	995.6 1	995.61
XSTR NPN 40V SOT-323 (SC-70) LEAD FREE	10	Q502,Q503,Q1304,Q1305,Q1306,Q1307,Q1308,Q1309,Q1400,Q1401	0.04	0.38

HID Global
MP1501 MTBF Report

Description	Qty	Ref Design	Device Fit	System Fit
DIODE, ESD 5V SOT23 ROHS TWO-LINE ESD PROTECTION	3	D810,D1100,D1200	5.85	17.54
DIODE TVS 600W 24A UNIDIRECTIONAL DO-214AA (SMBJ)	2	D1309,D1310	1.80	3.60
XSTR PNP 40V MMBT3906 TO-236AX LEAD FREE	4	Q1300,Q1301,Q1302,Q1303	0.04	0.15
CAP CER, 100NF ±10%, 100V, X7R, 0805	4	C1005,C1007,C1033,C1034	0.28	1.13
CAP X7R 10NF 50V 10% 0402 LEAD FREE	6	C301,C302,C307,C309,C320,C1010	0.28	1.69
RESISTOR, THICK-FILM, 560 OHM, ±1%, 0.063W, 0402	1	R1023	0.20	0.20
CAP COG 6.8PF 50V 2% 0402 LEAD FREE	4	C800,C801,C802,C803	0.28	1.13
RES FILM 10 OHM 0.125W (1/8W) 5% 1206 ROHS COMPLIANT	2	R1316,R1317	0.20	0.40
RES FILM 4.7K .063W 5% 0402 LEAD FREE	33	R306,R324,R500,R505,R506,R507,R508,R709,R805,R810,R811,R812,R813,R1100,R1244,R1247,R1250,R1308,R1309,R1310,R1311,R1314,R1315,R1318,R1319,R1320,R1322,R1326,R1328,R1330,R1332,R1336,R1338	0.20	6.59
RES FILM 1.0K OHM 0.063W (1/16W) 1% 0402 ROHS COMPLIANT	21	R501,R502,R509,R510,R710,R801,R802,R803,R806,R807,R808,R809,R814,R1400,R1403,R1404,R1407,R1408,R1409,R1410,R1411	0.20	4.20
RES FILM 10K OHM 0.063W (1/16W) 1% 0402 ROHS COMPLIANT	24	R708,R711,R712,R901,R902,R1021,R1022,R1038,R1101,R1102,R1103,R1104,R1105,R1106,R1107,R1108,R1109,R1110,R1111	0.20	4.79

Description	Qty	Ref Design	Device Fit	System Fit
		,R1112,R1401,R1402,R1405,R1406		
CAP X5R 22UF 25V 20% 0805	2	C315,C316	0.28	0.56
CAP CER 1UF 20% 6.3V X5R 0201	40	C407,C409,C412,C600,C601,C602,C603,C604,C605,C606,C607,C610,C611,C612,C613,C614,C615,C616,C620,C621,C622,C623,C624,C625,C626,C627,C628,C629,C630,C633,C634,C643,C644,C645,C647,C648,C1012,C1013,C1400,C1401	0.28	11.29
CAP CER 22UF 6.3V X5R 0603	8	C400,C401,C405,C418,C608,C609,C617,C618	0.28	2.26
CAP X7R .1UF 16V 10% 0402 LEAD FREE	35	C323,C512,C513,C514,C515,C632,C635,C646,C700,C804,C900,C901,C902,C905,C906,C907,C908,C909,C910,C911,C912,C913,C914,C915,C1011,C1014,C1101,C1103,C1107,C1108,C1109,C1111,C1234,C1300,C1303	0.28	9.88
CAP, SMD ELECTROLYTIC,LOW IMPEDANCE,47UF 50V,6.3X7.7, 20%, 105 DEGREES C	2	C300,C308	1.34	2.69
CAP, SMD SUPER-CAPACITORS 3.5V 0.22F - 20/80%, 10.8X10.7MM, - 25 C TO + 70 C	1	C329	1.05	1.05
CAPACITOR, CERAMIC, 47PF, 5%, COG, 50V, 0402	1	C327	0.28	0.28
CAP CER 10UF 16V 10% X5R 0603	12	C402,C403,C404,C406,C417,C903,C904,C1008,C1009,C1105,C1106,C1110	0.28	3.39
CAPACITOR, CERAMIC, CHIP, 10UF 20%, 50V, X5R 1206	12	C303,C306,C321,C322,C502,C503,C504,C506,C507,C508,C510,C511	0.28	3.39
CAP CER XR7 1000PF 10% 25V 0201	8	C636,C637,C638,C639,C640,C641,C642,C1233	0.28	2.26
CAP CER, 2.2UF ±10%, 10V, X5R, 0201	3	C619,C631,C1104	0.28	0.85
CAPACITOR, CERAMIC, 1NF, 5%, X7R, 1000V, 1812, SMT	2	C500,C1035	0.28	0.56
CAPACITOR, CERAMIC, 22NF, 10%, X7R, 50V, 0402	1	C1000	0.28	0.28
CAP CER, 3.3NF ±10%, X7R, 50V, 0402	1	C328	0.28	0.28

Description	Qty	Ref Design	Device Fit	System Fit
CAPACITOR, CERAMIC, CHIP, 10P, 5%, NPO, 50V, 0402	1	C324	0.28	0.28
CAPACITOR, CERAMIC, CHIP, 22PF, 5%, 50V, NPO, 0402	4	C1304,C1305,C1306,C1307	0.28	1.13
CAPACITOR, CERAMIC, CHIP, 18PF 5% 50V NPO 0402	2	C1017,C1018	0.28	0.56
CAPACITOR, CERAMIC, CHIP, 4.7UF, 20%, 10V, X5R, 0402	11	C408,C410,C411,C413,C414,C415,C416,C1015,C1100,C1102,C1207	0.28	3.10
CONN MICRO SD R/A 8WAY PUSH/PUSH W DETECT SMD	1	J1100	0.59	0.59
XTAL 25.000MHZ, 18PF, FTOL=30PPM, STAB=30PPM, -10C~+70C, 3.2X2.5MM SMD	1	Y1000	5.70	5.70
CRYSTAL, SMD, 32.7680KHZ, 7PF	1	Y801	5.70	5.70
XTAL CRYSTAL 24MHZ, CL=8PF, TOL: ±15PPM, SMD 2016	1	Y800	5.70	5.70
DIO ZENER 15V 200MW SOD-323F	3	D300,D501,D502	0.05	0.15
DIO TVS 5.0V SMBJ UNIDIRECTIONAL LEAD FREE	6	D1303,D1304,D1400,D1401,D1402,D1403	2.32	13.89
DIODE SCHOTTKY 40V 3.0A SMA	2	D304,D305	2.64	5.27
DIODE, LL4148, SMALL SIGNAL SILICON, MINI-MELF, 200MA	4	D1301,D1302,D1405,D1407	0.02	0.10
DIODE, SCHOTTKY, 100V, 0.15A, LOW FORWARD VOLTAGE, SOD-323	4	D302,D809,D1002,D1003	0.09	0.35
SMD 2 LINE COMMON MODE FILTER WITH ESD PROTECTION, 90OHMS, 25%,1210-6	1	FIL1201	63.41	63.41
FERRITE BEAD, 1K@100MHZ, 2A,100MOHMS, SMD, 1210	1	FB300	0.25	0.25
FILTER, SD CARD EMI FILTER AND ESD PROTECTION, 45OHM, 20PF, QFN16L	1	FL1100	0.29	0.29
FILTER, FERRITE BEAD, 1000R@0.1GHZ , 0.8R @ DC, 200MA, 0402	2	L1000,L1001	0.34	0.68
FUSE, PTC RESETTABLE 33V 1.1A SMD 2920	2	PTC500,PTC501	0.00	0.01
IC DUAL COMP SO8, SOIC8	2	U1300,U1301	0.14	0.27
IC, SERIAL NOR FLASH MEMORY, SPI - QUAD, 133MHZ 128MBIT, SOIC8	2	U1101,U1102	0.46	0.93
IC, 10/100 ETHERNET RMII PHY, 1.6-3.6V, 0 TO +85 DEGREES C,QFN-24	1	U1000	0.59	0.59
IC CRYPTO ELEMENT SOIC-8	1	U1103	0.16	0.16

Description	Qty	Ref Design	Device Fit	System Fit
IC,PMIC, 2.8-5.5V, 7 X LDOS, 5 X DC2DC, -40 TO 105C, WFQFN44L	1	U400	0.01	0.01
IC, SECURE BOOT CPU, ARM A7, 650MHZ, -40 TO 125C, TFBGA320	1	U600	0.55	0.55
IC ,BUCK, 3.8-40V, 3.5A, 570KHZ, SS, -40 TO +85C, SOIC-8EP	1	U301	0.10	0.10
IC, NAND FLASH, EMMC 5.1 8GB, -25 TO +85C, TFBGA-153	1	U1100	1.72	1.72
IC, DDR3L, 4GBIT (256M X 16), 933MHZ, 0 TO +95C, VFBGA -96	1	U900	34.76	34.76
IND, WIREWOUND, 4.7UH, ±20%, 10A, 0.015OHMS, SHIELDED, SMD 13.2X12.9X3.5.2MM SMD	1	L303	0.06	0.06
FERRITE BEAD, 120R@100MHZ, 0.05R @DC, 2A,0603	3	FIL1200,L508,L509	0.25	0.75
INDUCTOR, SHIELDED, POWER,1UH, ±20%, 3A, 0.056R 2.5 X 2.0MM SMT	4	L400,L401,L402,L403	0.60	2.40
RES SMD 22K OHM 5% 1/16W 0402	10	R1305,R1306,R1324,R1325,R1327,R1329,R1334,R1335,R1337, R1339	0.20	2.00
RESISTOR, CHIP, THICK-FILM, 12.1K +-1%, 0.063W, 0402	1	R1025	0.20	0.20
FLTR, FERRITE BEAD, 600OHM 0603 1A, LEAD FREE	2	R1245,R1246	0.25	0.50
RESISTOR, 0402, 453K, 1%, 1/16W	1	R319	0.20	0.20
RES FILM 13K OHM 1% 1/16W 0402	1	R323	0.20	0.20
RES, FILM, 12.4K OHM, 1%, 100PPM, 1/16W, 0402	1	R1212	0.20	0.20
RES, FILM, 3K OHM, 1%, 100PPM, 1/16W, 0402	1	R700	0.20	0.20
RES, FILM, 68.1K OHM, 1%, 100PPM, 1/16W, 0402	2	R301,R320	0.20	0.40
RES, FILM, 21K OHM, 1%, 100PPM, 1/16W, 0402	1	R1241	0.20	0.20
RES, FILM, 14K OHM, 1%, 100PPM, 1/16W, 0402	1	R321	0.20	0.20
RESISTOR, CHIP, THICK-FILM, 33R+-5%, 0.1W 0805	1	R302	0.20	0.20
RES, FILM, 33R OHM, 5%, 100PPM, 1/4W, 1206	4	R1302,R1304,R1312,R1313	0.20	0.80
RESISTOR, THICK FILM, CHIP, 47K, 1%, 0.063W, 0402	1	R815	0.20	0.20

Description	Qty	Ref Design	Device Fit	System Fit
RESISTOR, CHIP, THICK FILM, OR, +-5%, 0.063W, 0402	10	R600,R800,R804,R1000,R1001, R1004,R1013,R1014,R1048,R1049	0.20	2.00
RESISTOR, CHIP, THICK FILM, CHIP, 100K ±1%, 0.063W, 0402	4	R303,R503,R504,R1114	0.20	0.80
RESISTOR, THICK FILM, CHIP, 100R, 1%, 0.063W, 0402	1	R904	0.20	0.20
RESISTOR, THICK FILM, CHIP, 330R, 1%, 0.063W, 0402	2	R1017,R1019	0.20	0.40
RESISTOR, THICK FILM, CHIP, 33R, 1%, 0.063W, 0402	1	R1015	0.20	0.20
RESISTOR, THICK FILM, CHIP, 10R, 1%, 0.063W, 0402	1	R318	0.20	0.20
RESISTOR, THICK FILM, CHIP, 470R, 1%, 0.063W, 0402	1	R1249	0.20	0.20
RESISTOR, THICK FILM, CHIP, 2.2K 1% 0.063W 0402	6	R1303,R1307,R1321,R1323,R1331,R1333	0.20	1.20
RESISTOR, THICK FILM, CHIP, 1.5K, 1%, 0.063W, 0402	6	R703,R704,R705,R706,R1018,R1020	0.20	1.20
RESISTOR, CHIP, THICK-FILM, 240R +-1%, 0.063W 0402	2	R900,R903	0.20	0.40
RESISTOR, THICK FILM, CHIP, 12K 1% 50V 0.063W 0402	1	R305	0.20	0.20
RESISTOR, THICK FILM, CHIP, 200K, 1%, 0.063W, 0402	1	R322	0.20	0.20
RESISTOR, SMT, 75R, 5%, 0.1W, THICK FILM, 0603	4	R1002,R1043,R1044,R1045	0.20	0.80
RESISTOR, CHIP, THICK-FILM, 49.9R +-1% 0.1W 0603	4	R1005,R1006,R1007,R1008	0.20	0.80
RESISTOR, CHIP, THICK-FILM, 18R +-1%, 0.063W 0402	7	R701,R702,R1009,R1010,R1011 ,R1012,R1016	0.20	1.40
RLY DPDT 2A 5V SEALED TH	2	K1400,K1401	33.45	66.89
TRANSISTOR, NTMS4177PR2G, P-CHANNEL POWER MOSFET, VDS(MAX) -30V, LD(MAX) - 8.9A, SOIC8, SMT	3	Q300,Q500,Q501	0.04	0.12
TRANSISTOR, N-CHANNEL MOSFET, 0.115A. 60V, SOT23	1	Q1200	0.10	0.10
TVS, BI-DIR, 28V STANDOFF, 45.4V TO 59V MAX CLAMP, 1500W, DO214AB (SMC)	1	D301	5.85	5.85
TRANSORB, SM712, RS485, 12V TO -7V FULL RANGE, 400W, SOT23	2	D1300,D1308	0.06	0.11

Description	Qty	Ref Design	Device Fit	System Fit
TVS DIODE ARRAY, 4WAY, NON-ISOLATED, LOW CAPACITANCE, 3.3V, 40A, UDFN PACKAGE	1	D1001	0.80	0.80
CAPACITOR, CERAMIC, 470PF 5% 50V NPO 0402	1	C1016	0.28	0.28
DIODE ZENER SINGLE 5.1V 2% 200MW 2-PIN SOD-323F	4	D1311,D1312,D1313,D1314	0.05	0.20
Total FIT				1353.115
Environmental Factor				1.500
System Duty Cycle				100%
System FIT				2029.673
System MTBF				492,690

5 Appendix B — MTBF Input Factors

5.1 Failure Rate

$$\lambda = \lambda b * \pi 1 * \pi 2 * \pi 3 * \pi 4$$

where

λ = failure rate

λb = base failure rate

πt = operating temperature factor

πes = electrical stress factor

πq = quality factor

πec = environmental condition factor

5.2 Temperature Factor

The prediction process uses a Temperature Factor to model the effect of temperature on failure rate. The value of this factor is based on the device operating temperature and the type of device. The value is normalized to a temperature of 40°C, which produces a Temperature Factor of 1.0 for all device types. When actual device operating temperature differs from the normalized temperature, the actual device operating temperature may be used. In general, temperatures less than 40°C result in a factor less than 1 and temperatures greater than 40°C result in factors greater than 1. The prediction program contains temperature models for each component type which calculates the factor.

5.3 Electrical Stress Factor

The prediction process assumes an electrical stress percentage of 50% (electrical stress factor = 1). If the device's application produces electrical stress percentage higher or lower than this base value, then the failure rate must be adjusted using the electrical stress factor. The prediction program contains electrical stress models for each component type which calculates the factor.

Part	Electrical Stress Percentage
Capacitor	(Sum of applied dc voltage plus ac peak voltage) / (rated voltage)
Resistor, fixed	Applied power / rated power
Resistor, variable	(V ² _{in} / total resistance) / rated power
Relay, switch	Contact current / rated current
Diode, general	Average forward current / rated forward current
Diode zener	Actual zener current or power / rated current or power
Transistor	Power dissipated / rated power

5.4 Quality Factor

The device failure rates used for the prediction process reflect the expected field reliability performance of generic device types. The actual reliability of a specific device will vary as a function of the degree of effort and attention paid by an equipment manufacturer to factors such as device selection/application, supplier selection/control, electrical/mechanical design margins, equipment manufacture process control, and quality program requirements. The table below describes the four quality levels and presents the values for their associated Quality Factor:

Quality Level 0	<p>This level shall be assigned to commercial-grade, reengineered, remanufactured, reworked, salvaged, or gray-market components that are procured and used without device qualification, lot-to-lot controls, or an effective feedback and corrective action program by the primary equipment manufacturer or its outsourced lower-level design or manufacturing subcontractors. However, steps must have been taken to ensure that the components are compatible with the design application.</p> <p>Quality Factor = 6</p>
Quality Level 1	<p>This level shall be assigned to commercial-grade components that are procured and used without thorough device qualification or lot-to-lot controls by the equipment manufacturer. However,</p> <p>(a) steps must have been taken to ensure that the components are compatible with the design application and manufacturing process; and</p> <p>(b) an effective feedback and corrective action program must be in place to identify and resolve problems quickly in manufacture and in the field.</p> <p>Quality Factor = 3</p>
Quality Level 2	<p>This level shall be assigned to components that meet requirements (a) and (b) of Quality Level 1, plus the following:</p> <p>(c) purchase specifications must explicitly identify important characteristics (electrical, mechanical, thermal, and environmental) and acceptable quality levels (i.e. AQLs, Defects per Million, etc) for lot control;</p> <p>(d) devices and device manufacturers must be qualified and identified on approved parts/manufacture's lists (device qualification must include appropriate life and endurance tests);</p> <p>(e) lot-to-lot controls, either by the equipment manufacturer or the device manufacturer, must be in place at adequate AQLs/DPMs to ensure consistent quality.</p> <p>Quality Factor = 1</p>
Quality Level 3	<p>This level shall be assigned to components that meet requirements (a) thru (e) of Quality Levels 1 and 2 plus the following:</p> <p>(f) device families must be re-qualified periodically;</p> <p>(g) lot-to-lot controls must include early life reliability control of 100% screening (temperature cycling and burn-in), which, if the results warrant it, may be reduced to a "reliability audit" (i.e. a sample basis) or to an acceptable "reliability monitor" with demonstrated and accepted cumulative early failure values of less than 200ppm out to 10,000 hours;</p> <p>(h) where burn-in screening is used, the Percent Defective Allowed (PDA) shall be specified and shall not exceed 2% and</p> <p>(i) and ongoing, continuous reliability improvement program must be implemented by both the device and equipment manufacturers.</p> <p>Quality Factor = .8</p>

5.5 Environmental Condition Factor

The prediction process defines 6 environmental conditions. A separate prediction should be made for each environmental condition to which the equipment may be exposed. The prediction process uses an Environment Factor as a quantitative expression for a condition's effect on failure rate. The factor goes from 1 (ground-based, fixed, controlled environment) to 15 (for a space based commercial environment such as a commercial communication satellite).

Environment	Factor	Nominal Environmental Conditions
Ground, Fixed, Controlled	1	Vibration/shock stresses: Low Atmospheric variations: Low Temp cycling stresses: Low Application examples: Central offices, data center, environmentally controlled vaults, environmentally controlled remote shelters, and environmentally controlled customer premise areas.
Ground, Fixed, Uncontrolled (limited)	1.5	Vibration/shock stresses: Low to moderate Atmospheric variations: Low to moderate Temp cycling stresses: Moderate to High Application examples: Weather-protected remote terminals, outdoor equipment, and radio tower equipment.
Ground Fixed, Uncontrolled (moderate)	2.0	Vibration/shock stresses: Moderate to High Atmospheric variations: Low to moderate Temp cycling stresses: Moderate to High Application examples: Remote terminals and outdoor equipment in manholes, and near direct path of railroad, highway, and air traffic.
Ground, Mobile (both vehicular mounted and portable)	4.0	Vibration/shock stresses: Extreme Atmospheric variations: Low to moderate Temp cycling stresses: High Application examples: Equipment that can be in rapid motion relative to the ground, including cell phones and hand-held devices, portable operating equipment, and test equipment
Airborne, Commercial	6.0	Vibration/shock stresses: Extreme Atmospheric variations: High Temp cycling stresses: High Application examples: Passenger compartment of commercial aircraft
Space-based, Commercial (low earth orbit)	15.0	Vibration/shock stresses: Extreme Atmospheric variations: High Temp cycling stresses: High Application examples: Commercial satellites

5.6 Definition of Failure

The definition of a failure should be well understood. This is a crucial element in predicting system reliability parameters.

The following is not included in failure rate predictions:

- Manufacturing process-induced errors.
- Software failures.
- Failures from procedural errors.

Failures in systems with multiple functions may be hard to define. In complex equipment, it may be useful to distinguish between failures affecting maintenance or repair and those affecting service. For example, the failure of an LED is likely to cause a return, but may not cause a service outage. Consequently, LEDs should be included in the failure rate estimate when the estimate is used to determine return rates, but they could likely be disregarded if the estimate is used to determine service availability.